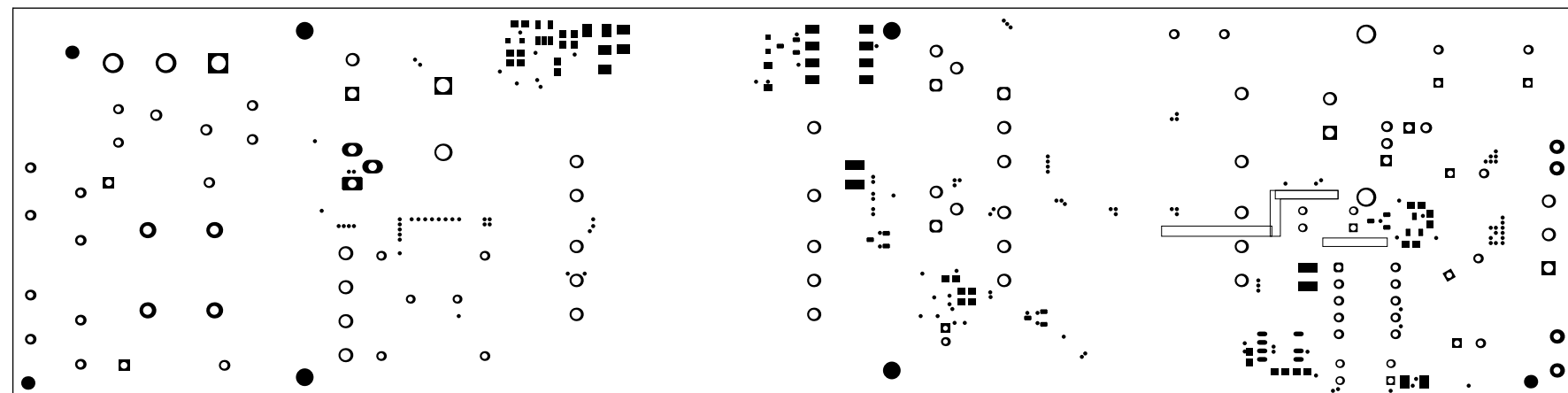
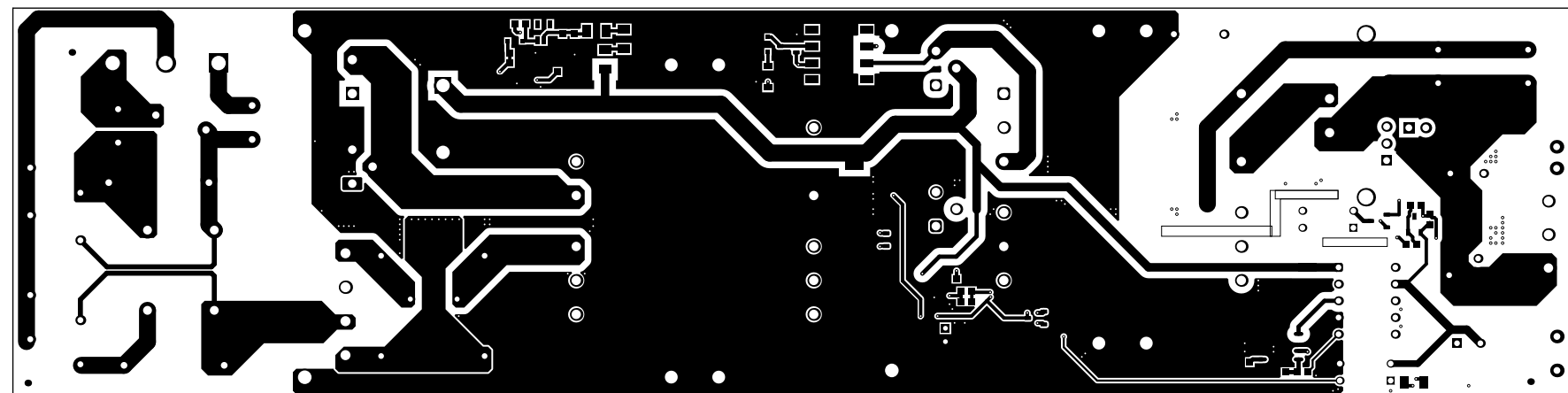


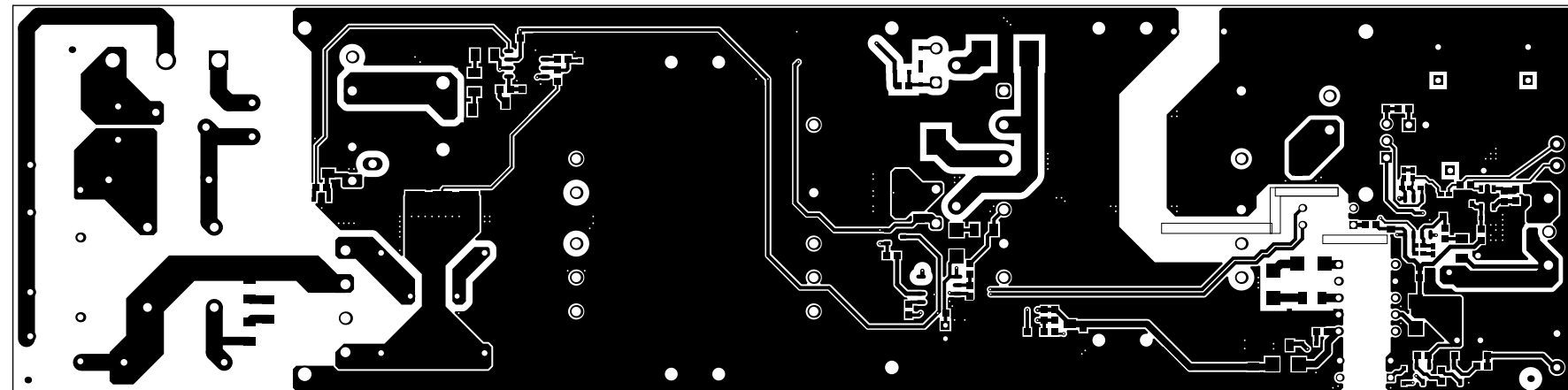
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01464	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: 1464		
PLOT NAME = Top Overlay	GENERATED : 11/13/2017 4:00:53 PM	TEXAS INSTRUMENTS	



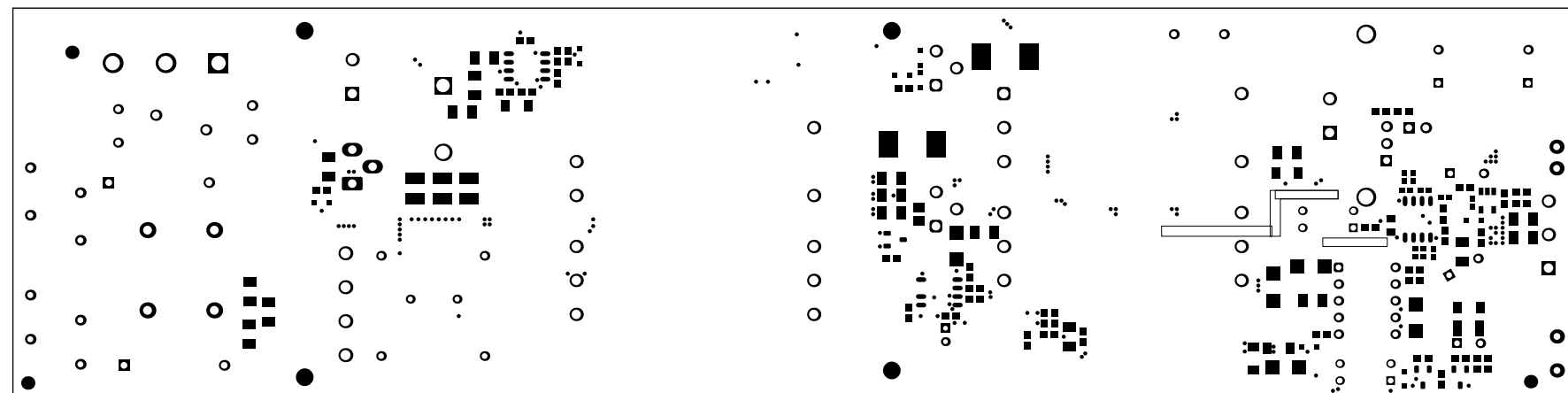
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01464	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: 1464		
PLOT NAME = Top Solder Mask	GENERATED : 11/13/2017 4:00:54 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01464	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: 1464		
PLOT NAME = Top Layer	GENERATED : 11/13/2017 4:00:56 PM	TEXAS INSTRUMENTS	

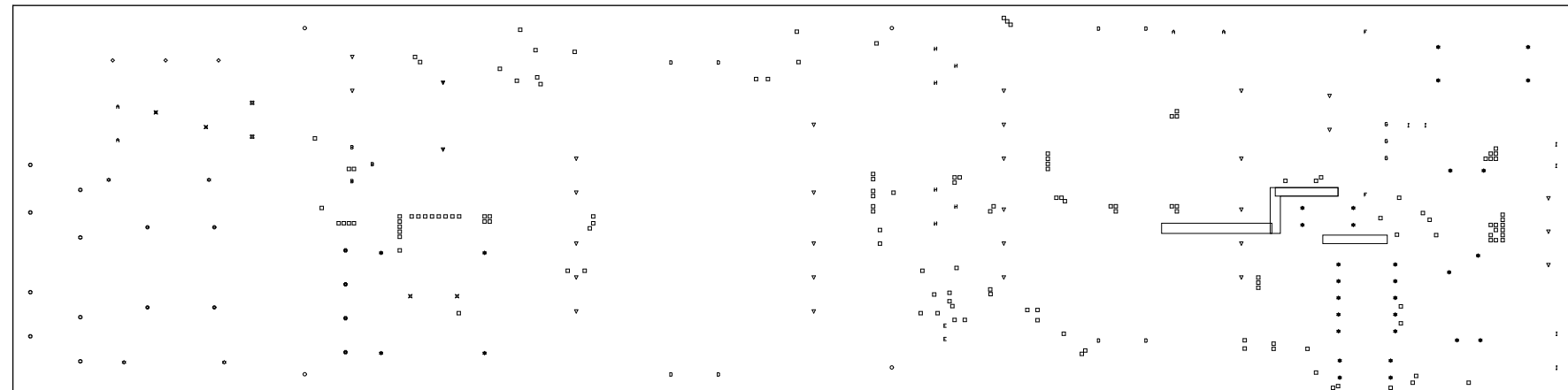


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01464	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: 1464		
PLOT NAME = Bottom Layer	GENERATED : 11/13/2017 4:00:57 PM		TEXAS INSTRUMENTS

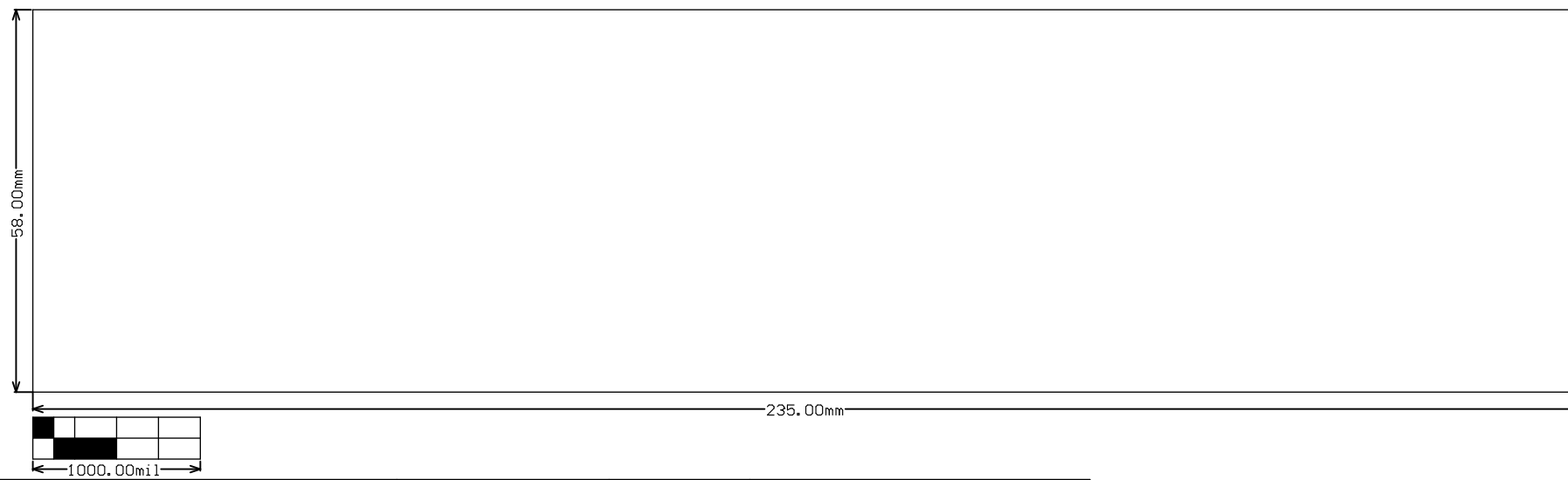


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01464	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: 1464		
PLOT NAME = Bottom Solder Mask	GENERATED : 11/13/2017 4:00:58 PM	TEXAS INSTRUMENTS	

Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
D	8	55.12mil (1.400mm)	NPTH	Round	Top Layer - Bottom Layer	
□	146	10.00mil (0.254mm)	PTH	Round	Top Layer - Bottom Layer	
E	2	28.00mil (0.711mm)	PTH	Round	Top Layer - Bottom Layer	
X	2	29.53mil (0.750mm)	PTH	Round	Top Layer - Bottom Layer	
☆	32	33.47mil (0.850mm)	PTH	Round	Top Layer - Bottom Layer	
⊕	8	35.00mil (0.889mm)	PTH	Round	Top Layer - Bottom Layer	
⊖	4	35.43mil (0.900mm)	PTH	Round	Top Layer - Bottom Layer	
☆	4	39.37mil (1.000mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	2	39.37mil (1.000mm)	PTH	Round	Top Layer - Bottom Layer	+3.94mil
I	6	40.00mil (1.016mm)	PTH	Round	Top Layer - Bottom Layer	
G	3	40.16mil (1.020mm)	PTH	Round	Top Layer - Bottom Layer	
X	2	43.31mil (1.100mm)	PTH	Round	Top Layer - Bottom Layer	
B	3	50.00mil (1.270mm)	PTH	Round	Top Layer - Bottom Layer	
H	6	51.18mil (1.300mm)	PTH	Round	Top Layer - Bottom Layer	
⊙	4	52.00mil (1.321mm)	PTH	Round	Top Layer - Bottom Layer	
▽	28	55.12mil (1.400mm)	PTH	Round	Top Layer - Bottom Layer	
⊕	4	59.06mil (1.500mm)	PTH	Round	Top Layer - Bottom Layer	
▽	2	78.74mil (2.000mm)	PTH	Round	Top Layer - Bottom Layer	
○	4	80.00mil (2.032mm)	PTH	Round	Top Layer - Bottom Layer	
◇	3	84.65mil (2.150mm)	PTH	Round	Top Layer - Bottom Layer	
F	2	87.01mil (2.210mm)	PTH	Round	Top Layer - Bottom Layer	
	275 Total					



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01464	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: 1464		
PLOT NAME = Drill Drawing	GENERATED : 11/13/2017 4:01:01 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01464	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: 1464		
PLOT NAME = Board Dimensions	GENERATED : 11/13/2017 4:01:03 PM	TEXAS INSTRUMENTS	

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